



Power line chokes

SurfIND, current-compensated SMD ring core double chokes
250 V AC, 120 ... 820 μ H, 24 ... 36 A, +70 °C

Series/Type: **B82725S2*A/B***

Date: August 2024



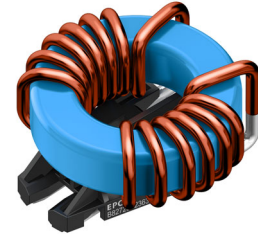
Rated voltage 250 V AC

Rated current 24 ... 36 A / +70 °C

Nominal inductance 120 ... 820 µH

Construction

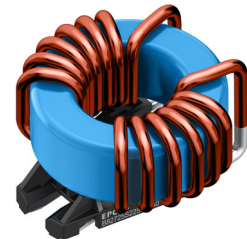
- Current-compensated ring core double choke
- Ferrite core with epoxy coating (UL 94 V-0)
- Plastic base plate (UL 94 V-0)
- Sector winding
- Self-leaded SMD terminals



B82725S2*A*

Features

- Approx. 0.6 ... 1% stray inductance for symmetrical interference suppression
- Low profile with defined height dimension and position of top surface for a heatsink-interface
- High rated currents at high ambient temperatures
- Two sizes for a wide range of values
- Glue-less design
- Suitable for reflow soldering
- Design complies with IEC/EN 60938-2
- RoHS-compatible



B82725S2*B*

Applications

- Suppression of common-mode interferences
- Switch-mode power conversion applications
- PCB assemblies for reflow-only soldering process

Terminals

- Ends of winding wires
- Hot-dip tinned

Marking

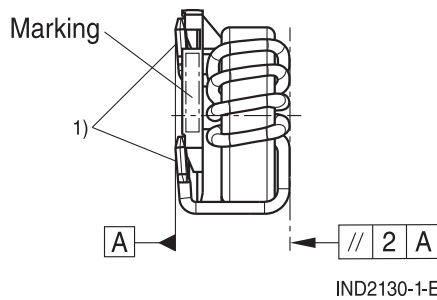
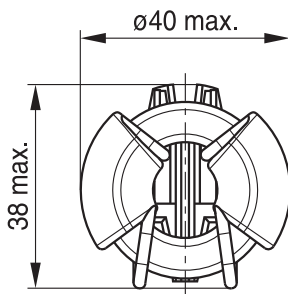
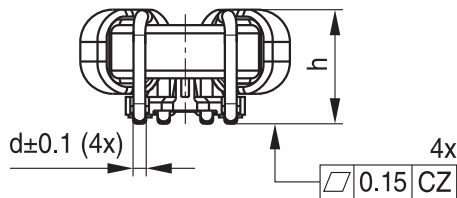
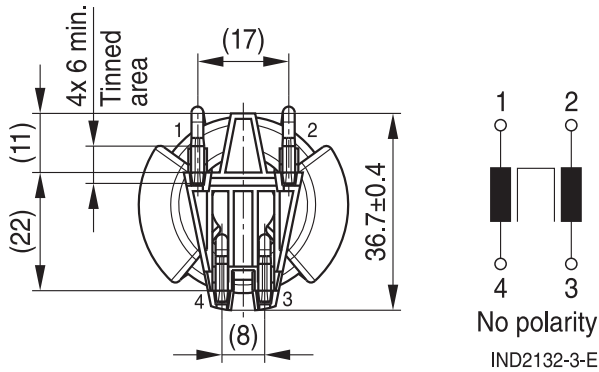
- Product brand (EPCOS), date of manufacture (YYWWD), production place identification code, ordering code, nominal inductance

Delivery mode and packing unit

- Blister tray in cardboard box
- Packing unit: 60 pcs./box

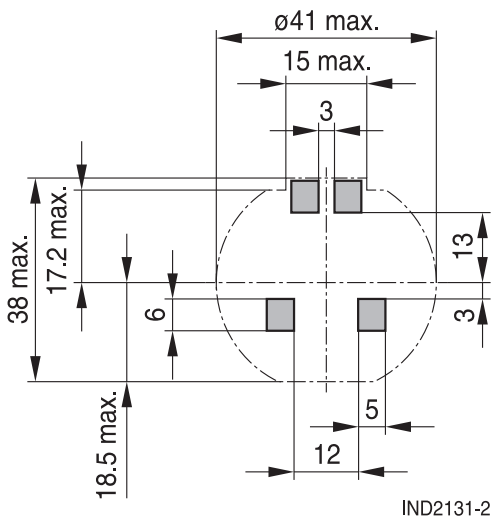


Dimensional drawing and pin configuration

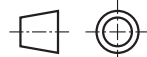


1) Terminals solderable tinned

Recommended PCB layout



Part tolerances to ISO 2768-c / ISO 8015.
Size ISO 14405 (E)
All dimensions in mm



IND2140-B-E

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Technical data and measuring conditions

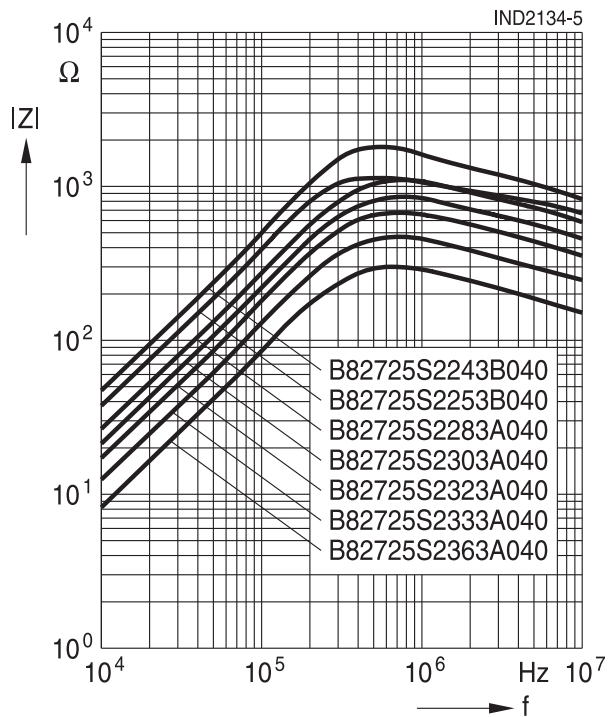
Rated voltage V_R	250 V AC (50/60 Hz)
Test voltage V_{test}	1500 V AC, 2 s (line/line)
Rated temperature T_R	+70 °C
Rated current I_R	Referred to 50/60 Hz and rated temperature
Rated current at +100 °C I_{R_100C}	Referred to 50/60 Hz and +100 °C ambient temperature
Nominal inductance L_N	Measured with Agilent 4284A at 100 kHz, 0.1 mA, +20 °C Inductance is specified per winding
Inductance tolerance	-30/+50% at +20 °C
Inductance decrease $\Delta L/L_0$	< 10% at DC magnetic bias with I_R , +20 °C
Stray inductance $L_{stray,typ}$	Measured with Agilent 4284A at 100 kHz, 5 mA, +20 °C, typical values
DC resistance R_{typ}	Measured at +20 °C, typical values, specified per winding
Solderability (lead free)	Sn96.5Ag3.0Cu0.5: +(245 ±3) °C, (3 ±0.3) s Wetting of soldering area ≥ 95% (to IEC 60068-2-58, test Td ₁ , method 1)
Resistance to soldering heat	Reflow profile to JEDEC J-STD 020F, 2 cycles, peak temperature +245 °C, measured on pin (to IEC 60068-2-58, test Td ₂ , method 2)
Climatic category	40/125/56 (to IEC 60068-1)
Pollution degree	P2 (to IEC 61558-1)
Storage conditions (packaged)	-25 °C ... +40 °C, ≤ 75% RH
Weight	approx. values

Characteristics and ordering codes

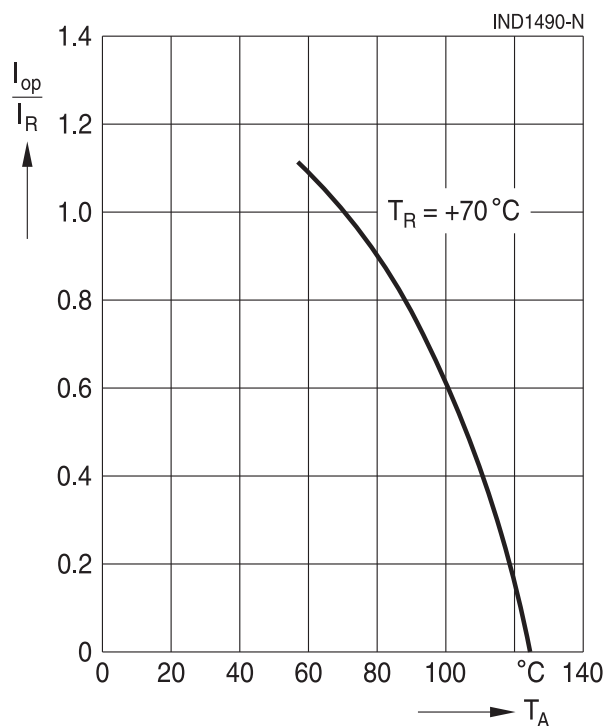
I_R	I_{R_100C}	L_R	$L_{stray,typ}$	R_{typ}	Weight	d	h	Ordering code
A	A	μH	μH	mΩ	g	mm	mm	
24	14	820	5	2.21	53	2.2	22.3±0.7	B82725S2243B040
25	14.5	650	4.3	1.95	49	2.2	22.3±0.7	B82725S2253B040
28	16	470	3.8	1.43	45	2.4	20.7±0.8	B82725S2283A040
30	17	360	2.8	1.30	43	2.4	20.7±0.8	B82725S2303A040
32	18	260	2.6	1.10	40	2.4	20.7±0.8	B82725S2323A040
33	19	180	1.5	0.93	38	2.4	20.7±0.8	B82725S2333A040
36	20	120	1	0.78	35	2.4	20.7±0.8	B82725S2363A040


Impedance $|Z|$ versus frequency f

measured with windings in parallel at +20 °C, typical values


Current derating I_{op}/I_R versus temperature T_A

rated temperature = +70 °C



Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition), online catalogs and in the data sheets.
 - Particular attention should be paid to the derating curves, if given. Derating applies in the case the ambient temperature in application exceeds the rated temperature of the component.
 - Ensure the operation temperature of the component in application not to exceed the maximum specified value or the upper climatic category temperature.
 - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pins only. Temperatures specified in relation to reflow soldering can also refer to the pins or terminals for products with larger thermal mass, as in such cases, the temperature difference to the top of the component is too big (e.g., high proportion of core within the component).
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. It is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.
 Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g., ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.
- The following points must be observed if the components are potted, sealed, or varnished in customer applications:
 - Many potting, sealing, or varnishing materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
 - It is necessary to check whether the potting, sealing or varnishing materials used attack or destroy the wire insulation, plastics, or glue.
 - The effect of the potting, sealing, or varnishing materials may change the high-frequency behavior of the components.
- Magnetic core materials such as ferrites are sensitive to direct impact. This can cause the core material to flake or lead to breakage of the magnetic core material.
- Any type of tension or pressure on the product may result in damage and affect its functionality and reliability.
 - The products are only to be attached to fixings or mounting holes provided for this purpose in accordance with the data sheet.
 - If additional mechanical forces are applied to the component, e.g., application of gap pads, it is necessary to check whether they attack or destroy any part of the component.
 - It is not permitted for the product specified in the data sheet to assume a mechanical function in the final application.
- Inductance value can drop if external metallic or magnetic parts will be put close to the coil or into the air gap of the coil or core or magnetic material.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

Display of ordering codes for TDK Electronics products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications, on the company website, or in order-related documents such as shipping notes, order confirmations and product labels. **The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products.** Detailed information can be found on the Internet under www.tdk-electronics.tdk.com/orderingcodes.

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1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application**. As a rule we are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether a product with the properties described in the product specification is suitable for use in a particular customer application.
2. We also point out that **in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified**. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
3. **The warnings, cautions and product-specific notes must be observed.**
4. In order to satisfy certain technical requirements, **some of the products described in this publication may contain substances subject to restrictions in certain jurisdictions (e.g. because they are classed as hazardous)**. Useful information on this will be found in our Material Data Sheets on the Internet (www.tdk-electronics.tdk.com/material). Should you have any more detailed questions, please contact our sales offices.
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Important notes

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